

CURRICULUM VITAE

PERSONAL PARTICULARS

Full Name	Muhammad Farid bin A Rahman
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E-mail	mhmmdfrd@gmail.com
Date of Birth	04 October 1988
Age	22
Gender	Male
Nationality	Malaysian

OBJECTIVE

To obtain a fruitful career and useful work experience in engineering with a company dealing with advanced technologies. Specifically, I am looking for a place where I could learn how to apply my technical knowledge and improve my technical skills as well as understanding what it is like to work in a team and at the same time bring you success in the industry.

ACADEMIC QUALIFICATION

Years	Institutions	Qualifications	Grade
2011	Meiji University, Kanagawa, Japan	Bachelor of Engineering in Mechanical Engineering	CGPA – 2.60
2009	Universiti Industri Selangor, Shah Alam, Malaysia	Diploma of Engineering in Mechanical Engineering	
2005	Maktab Rendah Sains MARA (MRSM) Jasin, Malaysia	Sijil Pelajaran Malaysia	9 1A's, 1 2A

OTHER CERTIFICATIONS, HONORS & SCHOLARSHIPS

TOEIC – Gold (895).
Japanese Language Proficiency Test (JLPT) – Level 2
University: MARA Education Foundation Scholarship Award recipient

ADDITIONAL SKILLS & INTEREST

Software	Advanced user of Microsoft Office applications: Word, Excel, and Powerpoint, sound knowledge in the usage of MATLAB, PTC Pro/ENGINEER Wildfire, c++ Programming, and LaTeX.
Languages	Fluent in written and spoken Bahasa Malaysia, English, and Japanese.
Interests	Football, Travel, and Music.

PREFERENCE

Willingness to Travel	Yes.
Willingness to Relocate	Yes.
Availability	After two (2) months notice
Expected Salary	RM 2700 (negotiable)

REFERENCES

Taichi Shiiba

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Suhaya Manap

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